

0083-0865-2

"RESPONSE UNDER 37 CFR 1.116-
EXPEDITED PROCEDURE EXAMINING
GROUP 2841"

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

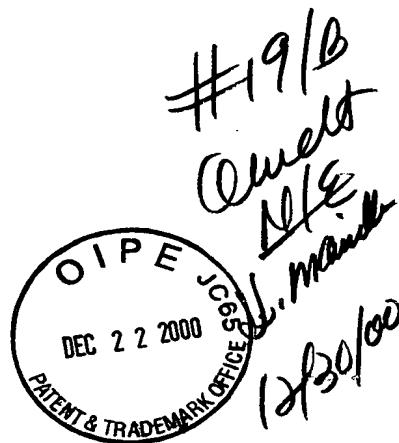
IN RE APPLICATION OF:

Masashi GOTOH, et al. ✓ : EXAMINER: CUNEO, K.

SERIAL NO.: 09/119,626 ✓ :

FILED: July 21, 1998 ✓ : GROUP ART UNIT: 2841

FOR: CIRCUIT BOARD HAVING
BONDING AREAS TO BE
JOINED WITH BUMPS BY
ULTRASONIC BONDING



AMENDMENT AFTER FINAL UNDER 37 CFR 1.116

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

2/7/01
SIR:

In response to the Official Action dated August 29, 2000, please amend the above-identified application as follows:

RECEIVED
DEC 29 2000
TC 2841 MAIL ROOM

IN THE SPECIFICATION

Please amend the specification as follows:

Page 1, line 24, change "making free use of related art totally" to --of the prior art--.

IN THE CLAIMS

Please cancel Claims 4-6, 8, and 10-12 without prejudice or disclaimer.

Please amend the following claims:

7. (Once Amended) A circuit board [for mounting a part having a plurality of bumps by ultrasonic bonding, said circuit board] comprising: